



T-39.09

N-Channel Enhancement-Mode Vertical DMOS Power FETs

Ordering Information

BV _{DSS} / BV _{DGS}	R _{DS(ON)} (max)	I _{D(ON)} (min)	Order Number / Package
			TO-220
100V	0.6Ω	4.0A	IRF510
60V	0.6Ω	4.0A	IRF511
100V	0.8Ω	3.5A	IRF512
60V	0.8Ω	3.5A	IRF513

Features

- Freedom from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C_{iss} and fast switching speeds
- Excellent thermal stability
- Integral Source-Drain diode
- High input impedance and high gain
- Complementary N- and P-Channel devices

Advanced DMOS Technology

These enhancement-mode (normally-off) power transistors utilize a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and negative temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex Vertical DMOS Power FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

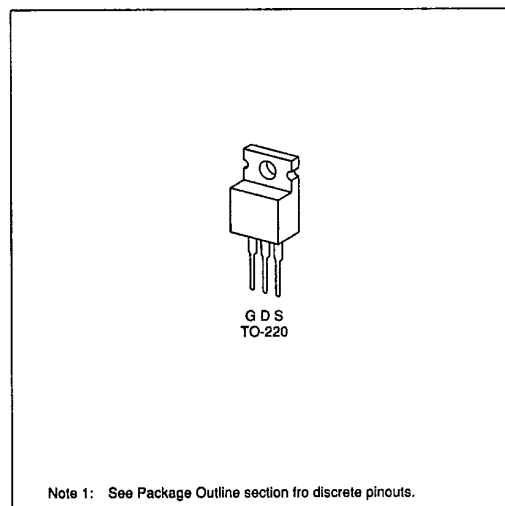
DataSheetDirectory

Applications

- Motor control
- Converters
- Amplifiers
- Switches
- Power supply circuits
- Drivers (Relays, Hammers, Solenoids, Lamps, Memories, Displays, Bipolar Transistors, etc.)

Package Options

(Note 1)



Absolute Maximum Ratings

Drain-to-Source Voltage	BV _{DSS}
Drain-to-Gate Voltage	BV _{DGS}
Gate-to-Source Voltage	± 20V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

*Distance of 1.6 mm from case for 10 seconds.

Thermal Characteristics

T-39-09

Package	I_D (continuous)*	I_D (pulsed)*	Power Dissipation @ $T_C = 25^\circ\text{C}$	θ_{JC} °C/W	θ_{JA} °C/W	I_{DR}	I_{DRM} *
IRF510	4.0A	16.0A	20W	80	6.4	4.0A	16.0A
IRF511	4.0A	16.0A	20W	80	6.4	4.0A	16.0A
IRF512	3.5A	14.0A	20W	80	6.4	3.5A	14.0A
IRF513	3.5A	14.0A	20W	80	6.4	3.5A	14.0A

* I_D (continuous) is limited by max rated T_J .

Electrical Characteristics (@ 25°C unless otherwise specified)

(Notes 1 and 2)

Symbol	Parameter	Min	Typ	Max	Unit	Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	IRF510, IRF512 100			V	$V_{GS} = 0, I_D = 250\mu\text{A}$
		IRF511, IRF513 60				
$V_{GS(th)}$	Gate Threshold Voltage	2.0		4.0	V	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$
I_{GSS}	Gate Body Leakage			500	nA	$V_{GS} = \pm 20V, V_{DS} = 0$
I_{DSS}	Zero Gate Voltage Drain Current			250	μA	$V_{GS} = 0, V_{DS} = \text{Max Rating}$
				1000		$V_{GS} = 0, V_{DS} = 0.8 \text{ Max Rating}$ $T_C = 125^\circ\text{C}$
$I_{D(ON)}$	ON-State Drain Current	IRF510, IRF511	4.0		A	$V_{GS} = 10V$
		IRF512, IRF513	3.5			$V_{DS} > I_{D(ON)} \times R_{DS(ON)}$ Max Rating
$R_{DS(ON)}$	Static Drain-to-Source ON-State Resistance	IRF510, IRF511		0.6	Ω	$V_{GS} = 10V, I_D = 2.0A$
		IRF512, IRF513		0.8		
G_{FS}	Forward Transconductance	1.0	1.5		S	$V_{DS} > I_{D(ON)} \times R_{DS(ON)}$ Max Rating $I_D = 2.0A$
C_{ISS}	Input Capacitance			150	pF	$V_{GS} = 0, V_{DS} = 25V$ $f = 1 \text{ MHz}$
C_{OSS}	Common Source Output Capacitance			100		
C_{RSS}	Reverse Transfer Capacitance			25		
$t_{d(ON)}$	Turn-ON Delay Time			20	ns	$V_{DD} = 0.5BV_{DSS}$ $I_D = 2.0A$ $R_S = 50\Omega$
t_r	Rise Time			25		
$t_{d(OFF)}$	Turn-OFF Delay Time			25		
t_f	Fall Time			20		
V_{SD}	Diode Forward Voltage Drop	IRF510, IRF511 2.5		2.0		
t_{rr}	Reverse Recovery Time		230		ns	$T_J = 150^\circ\text{C}, I_{SD} = 4.0A,$ $di_{F/dt} = 100A/\mu\text{S}$

Note 1: All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)

Note 2: All A.C. parameters sample tested.

Switching Waveforms and Test Circuit

